ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	IPC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docum level parts, t	ent is a declarati he declaration e	on of the su	bstances v s all lower	vithin the manufactu level materials for v	urer listed which the	item. Note manufactur	: if the item is an as rer has engineering	sembly with low responsibility.	
				Form Type Distribute					rials and N	ials and Mfg Information				
upplier Information														
Company name* Compan			npany unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2025-0	2025-09-13			
Contact Name Title - Contact			zt			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product Envi			viro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			esentative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product Env			wiro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Number		umber Mfr Item Name			Effective Date Version Manufacturing S		lanufacturing Site		Weight*	UOM	Unit Type		
	FDMD8	MD8680 FET 80V 4.7 n		nOhm PQFN56		2025-09-13		PI	РВВ		95.9	mg	Each	
Ianufacturing Proccess Informa	ntion						-	·						
Terminal Plating / Grid Array M	laterial 7	Ferminal Base A	Alloy	J-STD-020 MSL Ratin		Peak Proc	eak Process Body Temperat		ure Max Time at Peak Tem		ature Nun	nber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	nds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	20.3	mg	Supplier	Zinc (Zn)	7440-66-6		0.0264	mg
			Supplier	Iron (Fe)	7439-89-6		0.477	mg
			Supplier	Copper (Cu)	7440-50-8		19.7803	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0162	mg
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach Solder	11.9	mg	Supplier	Silver (Ag)	7440-22-4		0.2975	mg
			А	Lead (Pb)	7439-92-1	7a	11.0075	mg
			Supplier	Tin (Sn)	7440-31-5		0.595	mg
Lead Frame	25.6	mg	Supplier	Zinc (Zn)	7440-66-6		0.0211	mg
			Supplier	Iron (Fe)	7439-89-6		0.6144	mg
			Supplier	Copper (Cu)	7440-50-8		24.9325	mg
			Supplier	Phosphorus (P)	7723-14-0		0.032	mg
Mold Compound-Black	33.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.1357	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		30.0015	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0678	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.695	mg
Plating	2.2	mg	Supplier	Tin (Sn)	7440-31-5		2.2	mg